2SD1262, 2SD1262A

Silicon NPN triple diffusion planar type darlington

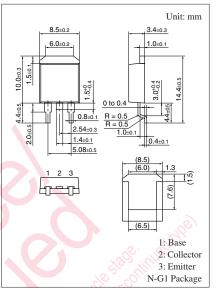
For midium speed power switching Complementary to 2SB0939, 2SB0939A

Features

- \bullet High forward current transfer ratio h_{FE}
- High-speed switching
- N type package enabling direct soldering of the radiating fin to the printed circuit board, etc. of small electronic equipment.

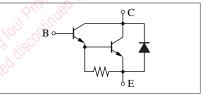
Absolute Maximum Ratings $T_c = 25^{\circ}C$							
Parameter	Symbol	Rating	Unit				
Collector-base voltage	2SD1262	V _{CBO}	60	V			
(Emitter open)	2SD1262A		80				
Collector-emitter voltage	2SD1262	V _{CEO}	60	V			
(Base open)	2SD1262A		80				
Emitter-base voltage (Coll	V _{EBO}	7	V				
Collector current	I _C	8	A				
Peak collector current	I _{CP}	12	Α				
Collector power dissipation		P _C	45	W			
	$T_a = 25^{\circ}C$		1.3				
Junction temperature		Tj	150	°C			
Storage temperature		T _{stg}	-55 to +150	°C			

Absolute Maximum Ratings $T_C = 25^{\circ}C$



Note) Self-supported type package is also prepared.

Internal Connection



Electrical Characteristics $T_C = 25^{\circ}C \pm 3^{\circ}C$

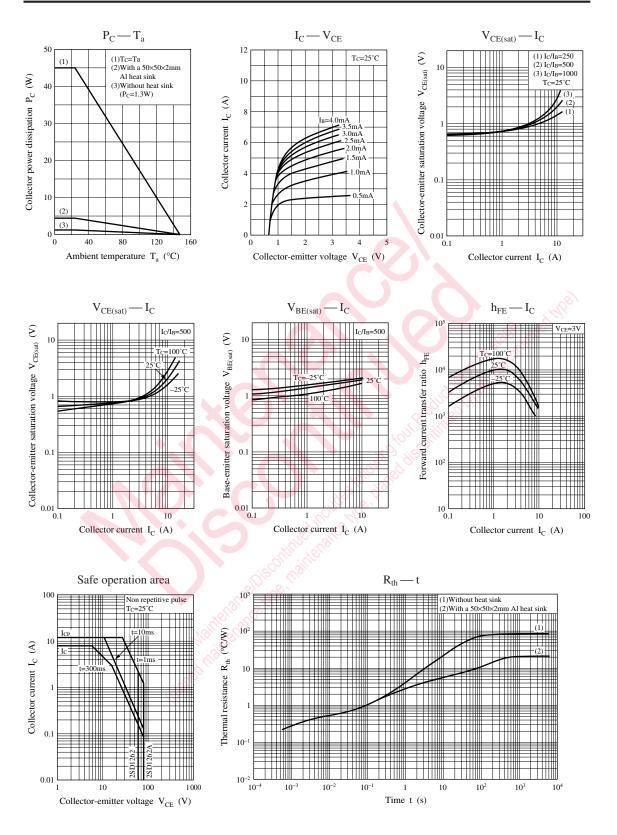
Parameter	• • (Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter voltage	2SD1262	V _{CEO}	$I_{\rm C} = 30 \text{ mA}, I_{\rm B} = 0$	60			V
(Base open)	2SD1262A		CONTRACTOR OF THE	80			
Collector-base cutoff	2SD1262	I _{CBO}	$V_{CB} = 60 \text{ V}, I_E = 0$			100	μΑ
current (Emitter open)	2SD1262A		$V_{CB} = 80 \text{ V}, I_E = 0$			100	
Emitter-base cutoff current (Co	llector open)	I _{EBO}	$V_{EB} = 7 V, I_C = 0$			2	mA
Forward current transfer rat	io 📣	h _{FE1} *	$V_{CE} = 3 V, I_C = 4 A$	1 0 0 0		10000	_
		h _{FE2}	$V_{CE} = 3 V, I_C = 8 A$	500			
Collector-emitter saturation	voltage	V _{CE(sat)}	$I_{C} = 4 A, I_{B} = 8 mA$			1.5	V
Base-emitter saturation volt	age	V _{BE(sat)}	$I_{\rm C} = 4 \text{ A}, I_{\rm B} = 8 \text{ mA}$			2.0	V
Transition frequency		f _T	$V_{CE} = 10 \text{ V}, I_C = 0.5 \text{ A}, f = 1 \text{ MHz}$		20		MHz
Turn-on time		t _{on}	$I_C = 4 A$		0.5		μs
Strage time		t _{stg}	$I_{B1} = 8 \text{ mA}, I_{B2} = -8 \text{ mA}$		4.0		μs
Fall time		t _f	$V_{CC} = 50 V$		1.0		μs

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. *: Rank classification

Rank	R	Q	Р
h _{FE1}	1000 to 2500	2000 to 5000	4000 to 10000

Panasonic



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